



*Image may not represent actual product

General Specifications

Pin Count	67 pin (M Key)
Form Factor	M.2 (80mm)
Unformatted Capacity	256GB
Cache	N/A

Default Format	Unformatted
Voltage	3.3V
Interface	PCIe 4.0 x4, NVMe 1.4
Warranty	1 Year

Endurance/Power/Performance

Max Read Speed*	3800 MB/s
Max Write Speed*	1700 MB/s
Seq. Read Speed**	3800 MB/s
Seq. Write Speed**	1700 MB/s
4k Random Read***	110000 IOPs
4k Random Write***	245000 IOPs
Endurance (TBW)	248

Active Power	3400 mW
Idle Power	1500 mW
Sleep Power	5 mW
Shock Tolerance	1500G(0.5ms duration, half sine wave)
Vibration Tolerance	20G(Peak,80-2000Hz)
MTBF	1,500,000 Hrs
DWPD	0.85

NAND Specifications

NAND Manufacturer	Kioxia
NAND Part Number	TA5AG95AYV
NAND Type	TLC
NAND Geometry	3D BIC5S

NAND Config.	1Tbit
NAND Quantity	2
NAND Package	BGA-132
NAND Technology	Dual Plane

*Maximum speeds are determined using ATTO Disk Benchmark

**Maximum Sequential speeds measured using HD Tune Pro 5.75

***Maximum I/O performance is measured using IOMeter 2010, 4K bytes Random

Environment

Operating Temp	Extended (0 to 85 C)
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Storage Temp	Storage (-40 to +85 C)
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Controller Specifications

Controller Mfg.	Phison
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Controller PN	PS5021-E21T
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Wear Level Static	Enabled
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Wear Level Dynamic	Enabled
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Power Loss Protection	No
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RAID Support	Yes
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SMART Support	Yes
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TRIM Support	Yes
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ECC	LDPC Gen4 + RAID
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Data Encryption	TCG Pyrite 2.0 (AES 256-bit)
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Certifications

ROHS	Yes
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Scope of Work

Industrial temperature controller with Commercial temperature NAND.

Pin Out Diagram

Pin Assignment and Description

Pin No.	PCIe Pin	Description	Pin No.	PCIe Pin	Description
1	GND	CONFIG_3 = GND	44	ALERT#(O) (0/1.8V)	Alert notification to master; Open Drain with pulUp on platform; Active low.
2	3.3V	3.3V source	45	GND	Ground
3	GND	Ground	46	N/C	No connect
4	3.3V	3.3V source	47	PERn0	PCIe RX Differential signal defined by the PCI Express M.2 spec
5	PETn3	PCIe TX Differential signal defined by the PCI Express M.2 spec	48	N/C	No connect
6	N/C	No connect	49	PERp0	PCIe RX Differential signal defined by the PCI Express M.2 spec
7	PETp3	PCIe TX Differential signal defined by the PCI Express M.2 spec	50	PERST#(I)(0/3.3V)	PE-Reset is a functional reset to the cards defined by the PCIe Mini CEM specification.
8	N/C	No connect	51	GND	Ground
9	GND	Ground	52	CLKREQ#(I/O)(0/3.3V)	Clock Request is a reference clock request signal as defined by the PCIe Mini CEM specification; Also used by L1 PM Substates.
10	LED1#	Open drain, active low signal. These signals are used to allow the addn card to provide status indicators via LED devices that will be provided by the system.	53	REFCLKn	PCIe Reference Clock signals (100 MHz) defined by the PCI Express M.2 spec.
11	PERn3	PCIe RX Differential signal defined by the PCI Express M.2 spec	54	PEWAKE#(I/O)(0/3.3V)	PCIe PME Wake. Open Drain with pull up on platform; Active Low.
12	3.3V	3.3V source	55	REFCLKp	PCIe Reference Clock signals (100 MHz) defined by the PCI Express M.2 spec.
13	PERp3	PCIe RX Differential signal defined by the PCI Express M.2 spec	56	Reserved for MFG DATA	Manufacturing Data line. Used for SSD manufacturing only Not used in normal operation. Pins should be left N/C in platform Socket.
14	3.3V	3.3V source	57	GND	Ground
15	GND	Ground	58	Reserved for MFG CLOCK	Manufacturing Clock line. Used for SSD manufacturing only. Not used in normal operation. Pins should be left N/C in platform Socket.
16	3.3V	3.3V source	59	Module Key M	Module Key
17	PETn2	PCIe TX Differential signal defined by the PCI Express M.2 spec	60	Module Key M	
18	3.3V	3.3V source	61	Module Key M	
19	PETp2	PCIe TX Differential signal defined by the PCI Express M.2 spec	62	Module Key M	
20	N/C	No connect	63	Module Key M	
21	GND	Ground	64	Module Key M	
22	N/C	No connect	65	Module Key M	
23	PERn2	PCIe RX Differential signal defined by the PCI Express M.2 spec	66	Module Key M	
24	N/C	No connect	67	N/C	No connect
25	PERp2	PCIe RX Differential signal defined by the PCIe Express M.2 spec	68	SUSCLK(32KHz) (I)(0/3.3V)	32.768 kHz clock supply input that is provided by the platform chipset to reduce power and cost for the module.
26	N/C	No connect	69	N/C	PEDET (NC-PCIe)
27	GND	Ground	70	3.3V	3.3V source
28	N/C	No connect	71	GND	Ground
29	PETn1	PCIe TX Differential signal defined by the PCI Express M.2 spec	72	3.3V	3.3V source
30	N/C	No connect	73	GND	Ground
31	PETp1	PCIe TX Differential signal defined by the PCI Express M.2 spec	74	3.3V	3.3V source
32	N/C	No connect	75	GND	Ground
33	GND	Ground			
34	N/C	No connect			
35	PERn1	PCIe RX Differential signal defined by the PCI Express M.2 spec			
36	N/C	No connect			
37	PERp1	PCIe RX Differential signal defined by the PCI Express M.2 spec			
38	N/C	No connect			
39	GND	Ground			
40	SMB_CLK (I/O)(0/1.8V)	SMBus Clock; Open Drain with pulUp on platform			
41	PETn0	PCIe TX Differential signal defined by the PCI Express M.2 spec			
42	SMB_DATA (I/O)(0/1.8V)	SMBus Data; Open Drain with pulUp on platform.			
43	PETp0	PCIe TX Differential signal defined by the PCI Express M.2 spec			

